







**LIGHT ELECTRONICS CO., LTD.**

**Photo Transistor Diode Specification**

●Commodity: Photo Transistor

●Ic(on) Bin Code ( $V_{CE}=5V$ ,  $E_e=1mW/cm^2$ )

| BIN CODE | Min. (mA) | Max. (mA) |
|----------|-----------|-----------|
| X2       | 3.7       | 4.4       |
| X3       | 4.4       | 5.3       |



## LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures (Fig.1).

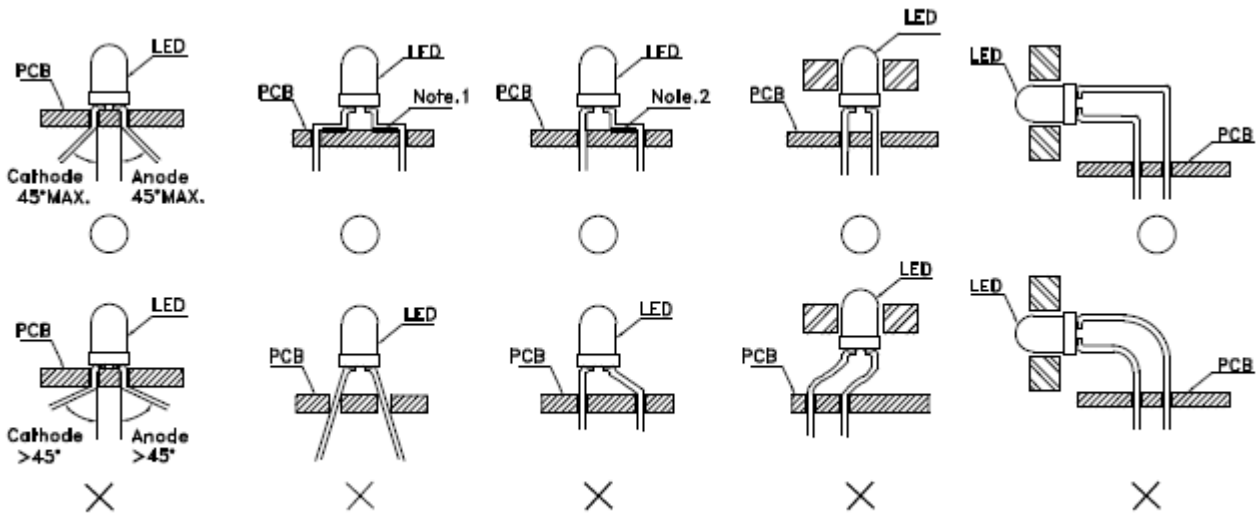


Fig. 1

“ ” Correct mounting method “X” Incorrect mounting method

Note 1-2: Do not route PCB trace in the contact area between the lead frame and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit (Fig.2).

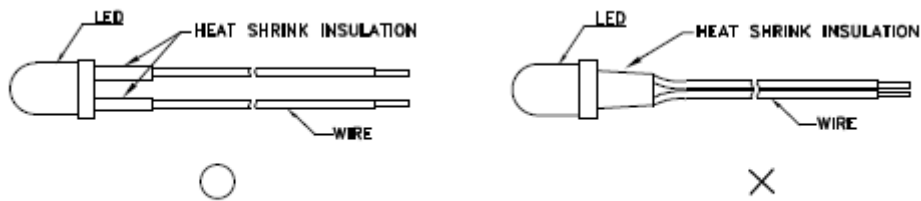


Fig. 2

3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

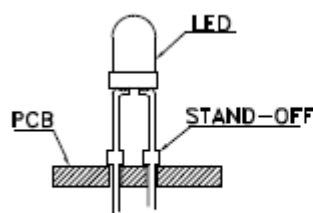


Fig. 3

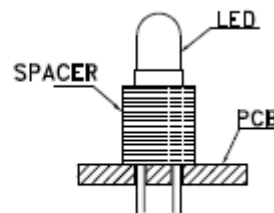
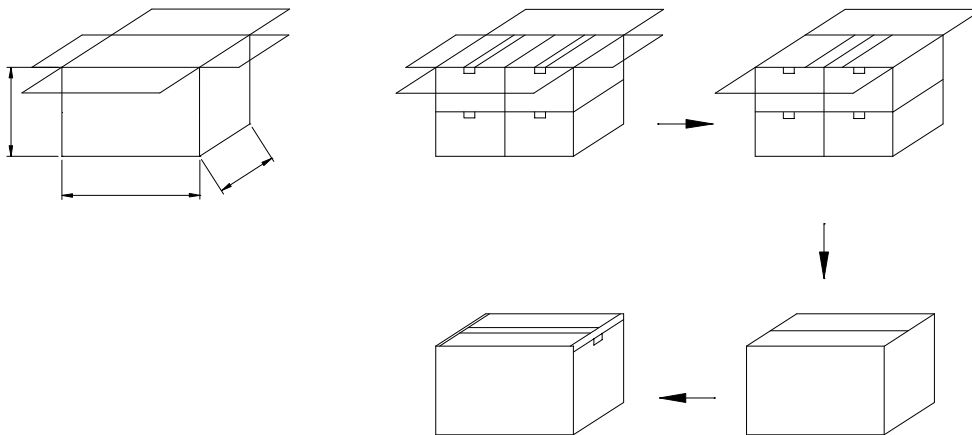
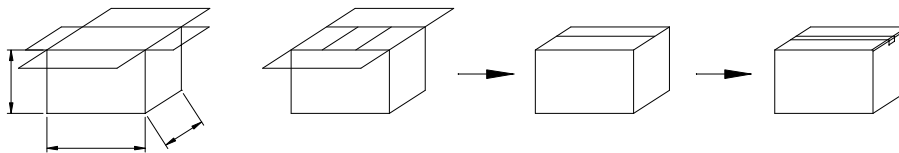
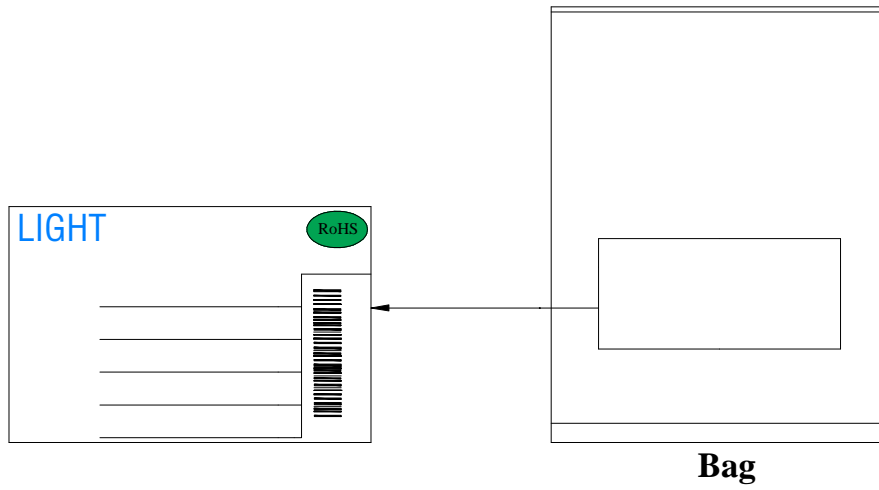


Fig. 4





## PACKAGE



| Bag minimum volume<br>(pcs / Bag) | Bag volume<br>(pcs / Bag) | Inner box volume<br>(Bag / box) | Outer carton volume<br>(Box / Carton) |
|-----------------------------------|---------------------------|---------------------------------|---------------------------------------|
| 500                               | 1000                      | 10                              | 4                                     |